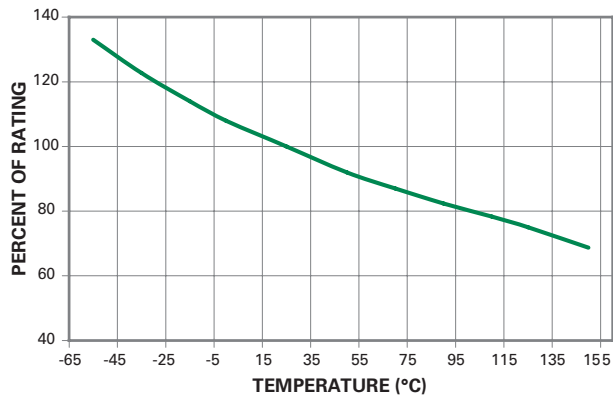


Temperature Re-rating Curve



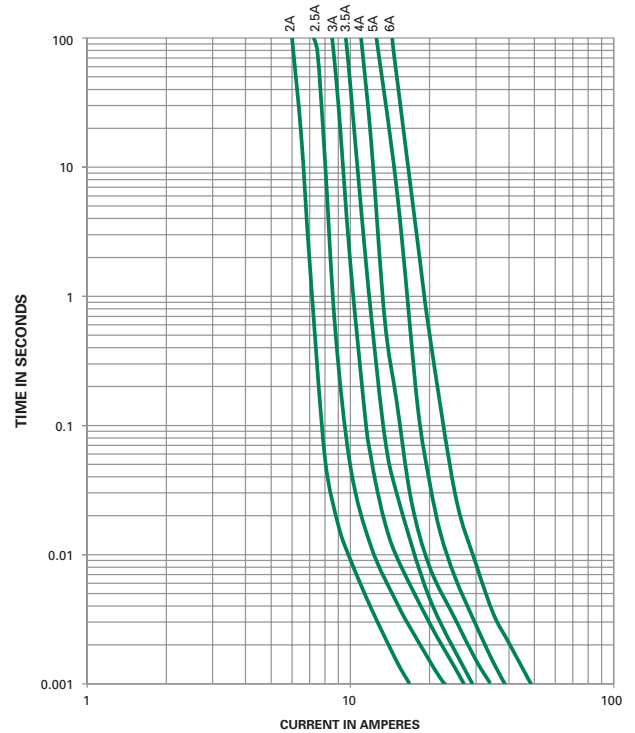
Note:

1. Re-rating depicted in this curve is in addition to the standard re-rating of 20% for continuous operation.

For continuous operation at 75 degrees celsius, the fuse should be re-rated as follows:

$$I = (0.80)(0.85)I_{\text{RAT}} = (0.68)I_{\text{RAT}}$$

Average Time Current Curves

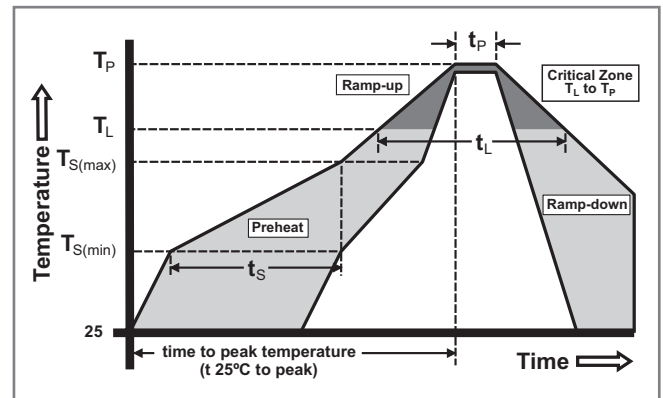


Soldering Parameters

Reflow Condition		Pb – free assembly
Pre Heat	- Temperature Min ($T_{s(\min)}$)	150°C
	- Temperature Max ($T_{s(\max)}$)	200°C
	- Time (Min to Max) (t_s)	60 – 180 seconds
Average Ramp-up Rate (Liquidus Temp (T_L) to peak)		3°C/second max.
$T_{s(\max)}$ to T_L - Ramp-up Rate		5°C/second max.
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		10 – 30 seconds
Ramp-down Rate		6°C/second max.
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

Wave Soldering

260°C, 10 seconds max.

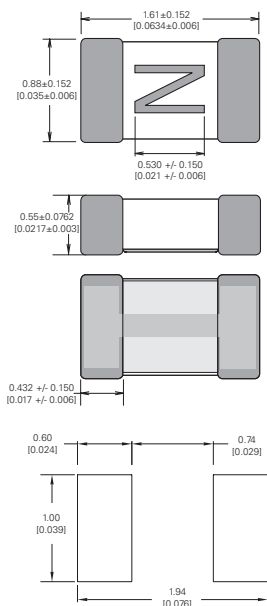


Product Characteristics

Materials	Body: Advanced Ceramic Terminations: Ag / Ni / Sn (100% Lead-free) Element Cover Coating: Lead-free Glass
Moisture Sensitivity Level	IPC/JEDEC J-STD-020, Level 1
Solderability	IPC/ECA/JEDEC J-STD-002, Condition C
Humidity Test	MIL-STD-202, Method 103, Conditions D
Resistance to Solder Heat	MIL-STD-202, Method 210, Condition B
Moisture Resistance	MIL-STD-202, Method 106
Thermal Shock	MIL-STD-202, Method 107, Condition B
Mechanical Shock	MIL-STD-202, Method 213, Condition A
Vibration	MIL-STD-202, Method 201
Vibration, High Frequency	MIL-STD-202, Method 204, Condition D
Dissolution of Metallization	IPC/ECA/JEDEC J-STD-002, Condition D
Terminal Strength	IEC 60127-4

High Temperature Storage	MIL-STD-202, Method 108 with exemptions
Thermal Shock Test	JESD22 Method JA-104, Test Conditions B and N
Biased Humidity	MIL-STD-202, Method 103, 85C/85% RH with 10% operating power for 1000 hrs
Operational Life	MIL-STD-202, Method 108, Test Condition D
Resistance to Solvents	MIL-STD-202, Method 215
Mechanical Shock	MIL-STD-202, Method 213, Test Condition C
High Frequency Vibration	MIL-STD-202, Method 204
Resistance to Soldering Heat	MIL-STD-202, Method 210, Test Condition B
Solderability	JESD22-B102E Method 1
Terminal Strength for SMD	AEC Q200-006
Board Flex	AEC Q200-005
Electrical Characterization	3 Temperature Electrical

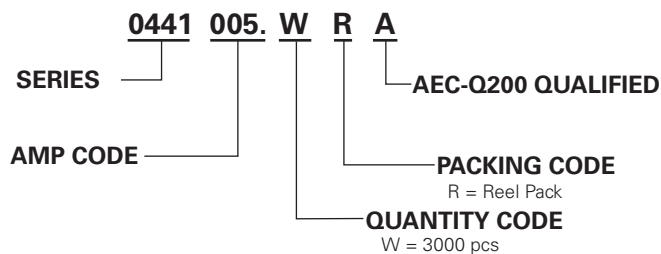
Dimensions



Part Marking System

Amp Code	Marking Code
002.	N
02.5	O
003.	P
03.5	R
004.	S
005.	T
006.	U

Part Numbering System



Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code
8mm Tape and Reel	EIA-481, IEC 60286, Part 3	3000	WRA